

**\*\*INFORMAL TRANSMISSION \*\***

PATENT

Docket No. 150.0093 0102

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Marsh	)	Group Art Unit:	2823
	)		
Serial No.: 09/812,157	)	Examiner:	Unknown
Confirmation No.: 2941	)		
	)		
Filed: March 19, 2001	)		
	)		
For: METHODS FOR PATTERNING METAL LAYERS FOR USE			
WITH FORMING SEMICONDUCTOR DEVICES (As Amended)			

**FACSIMILE TRANSMISSION TO THE PTO**

Assistant Commissioner for Patents  
Attn: Ms. Dorothy Dixon  
Rm. 324  
Washington, D.C. 20231

FAX NUMBER: 703/308-7722  
Total Pages (including cover page): 2  
Time: 8:25 AM (Central Time)  
(Transmission must be complete by  
midnight eastern time.)

Dear Ms. Dixon:

From our conversation this morning, I understand that page 1 of the Preliminary Amendment filed in the above-identified application has been inadvertently damaged or lost. Pursuant to your request, please find a COPY of the requested page attached herewith.

If you require any additional information, please feel free to contact me.

Mueting, Raasch & Gebhardt, P.A.  
Customer Number: 26813

July 12, 2001  
Date

By: Matthew W. Adams  
Matthew W. Adams  
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If you do not receive all pages, please contact us at (612)305-1220 (ph) or (612)305-1228 (fax).

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JUL 12 2001

TECHNOLOGY CENTER 2800

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D. Davis  
4-28-01  
PATENT

Docket No. 150.00930102

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Marsh ) Group Art Unit: Unknown  
Serial No.: Unknown )  
(Parent 09/146,408) ) Examiner: Unknown  
Filed: Unknown )  
(Parent: September 3, 1998) )  
For: METHODS FOR PATTERNING METAL LAYERS FOR USE WITH  
FORMING SEMICONDUCTOR DEVICES (As Amended)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Attn: Box Patent Application  
Washington D.C. 20231

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Dear Sir:

Before taking the application filed herewith up for examination, please amend the same  
as follows:

In the Title

✓  
Please replace the title with -- METHODS FOR PATTERNING METAL LAYERS FOR  
USE WITH FORMING SEMICONDUCTOR DEVICES --

In the Specification

Please insert the following new paragraph at page 1, line 3 (immediately before the "Field  
of the Invention" heading) as instructed in the Request filed herewith:

AI -- This is a continuation of application Serial No. 09/146,408, filed September 3, 1998,  
(pending), which is incorporated herein by reference. --

COPY